

N-Channel Enhancement Mode MOSFET

TDM3436A

DESCRIPTION

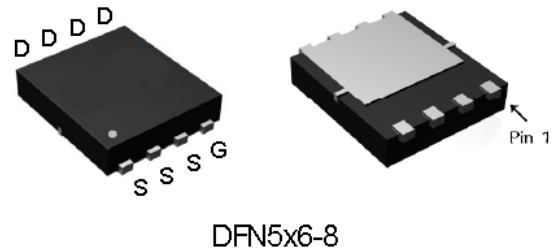
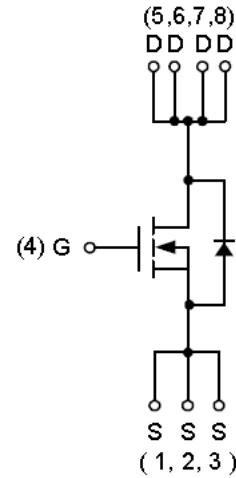
The TDM3436A uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

- $R_{DS(ON)} < 3.2m\Omega$ @ $V_{GS}=10V$
 $R_{DS(ON)} < 5.3m\Omega$ @ $V_{GS}=4.5V$
- High Power and current handling capability
- Lead free product is available
- Surface Mount Package

Application

- PWM applications
- Load switch
- Power management

ABSOLUTE MAXIMUM RATINGS($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current @ Continuous (Note 1)	I_D ($T_C=25^\circ\text{C}$)	89	A
	I_D ($T_C=100^\circ\text{C}$)	71	A
Drain Current @ Current-Pulsed (Note 2)	I_{DM} ($T_C=25^\circ\text{C}$)	240	A
Avalanche Current	I_{AS}	54	A
Single Pulse Avalanche Energy (Note 3)	EAS	145	mJ
Maximum Power Dissipation ($T_A=25^\circ\text{C}$) (Note 4)	P_D	22	W
Maximum Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 To 150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	55	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Case (Note 1)	$R_{\theta JC}$	1.7	$^\circ\text{C}/\text{W}$

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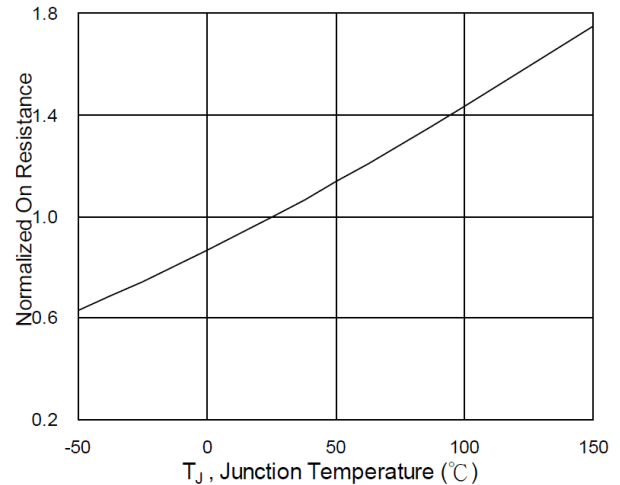
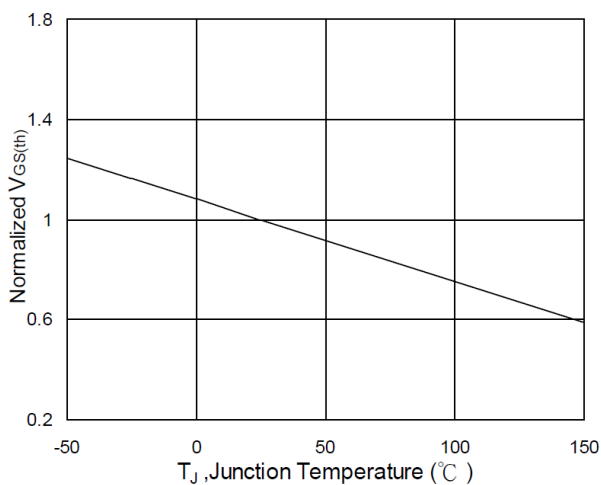
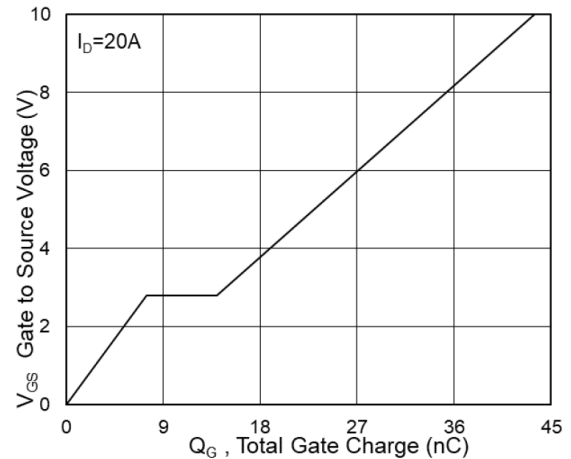
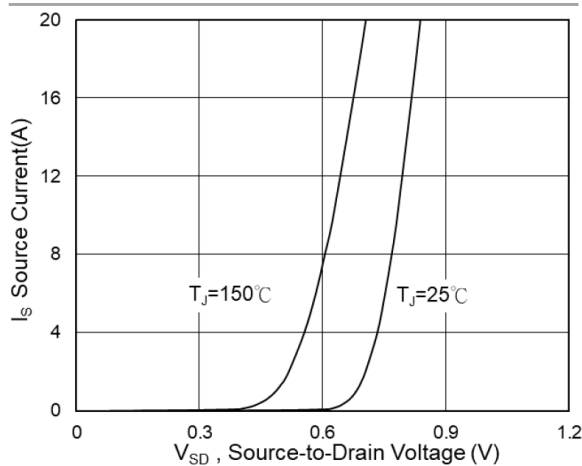
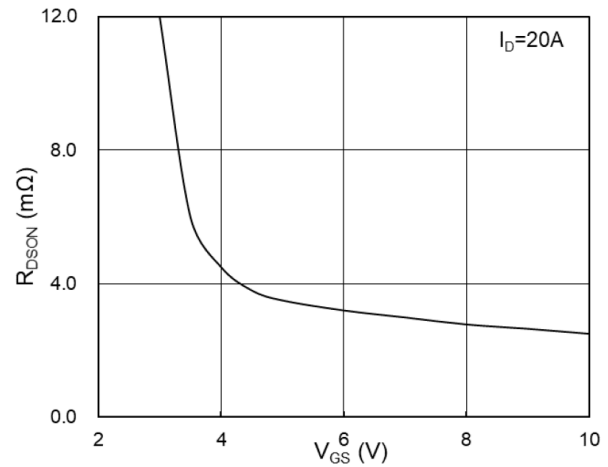
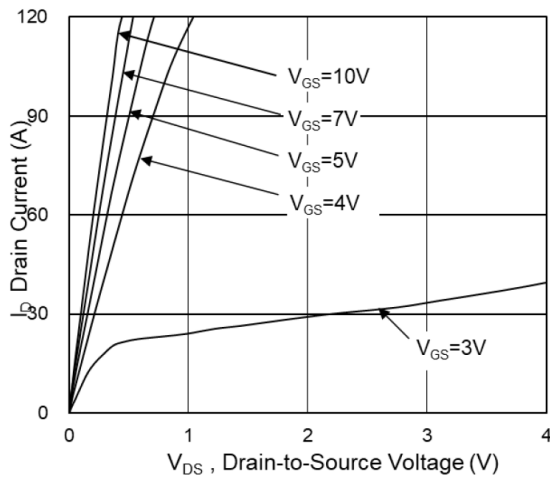
ELECTRICAL CHARACTERISTICS ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	40	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250μA	1.2	1.7	2.2	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μ A
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	± 100	nA
Drain-Source On-State Resistance (Note2)	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	2.5	3.2	mΩ
		V _{GS} =4.5V, I _D =15A	-	3.8	5.3	mΩ
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	V _{DS} =20V,V _{GS} =0V, F=1.0MHz	-	2648	-	PF
Output Capacitance	C _{oss}		-	899	-	PF
Reverse Transfer Capacitance	C _{rss}		-	571	-	PF
SWITCHING CHARACTERISTICS (Note 3)						
Turn-on Delay Time	t _{d(on)}	V _{DS} =20V, V _{GS} =10V, R _G =3Ω, I _D =20A	-	10	-	nS
Turn-on Rise Time	t _r		-	5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	33	-	nS
Turn-Off Fall Time	t _f		-	6.5	-	nS
Total Gate Charge	Q _g	V _{DS} =20V, I _D =20A, V _{GS} =4.5V	-	22.7	-	nC
Gate-Source Charge	Q _{gs}		-	7.5	-	nC
Gate-Drain Charge	Q _{gd}		-	5.5	-	nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Continuous Source Current (Note 1,5)	I _s	V _G =V _D =0V, Force Current	-	-	30	A
Diode Forward Voltage (Note 2)	V _{SD}	V _{GS} =0V,I _S =20A	-	0.8	1.1	V

NOTES:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=54A$
4. The power dissipation is limited by junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Operating Characteristics



Typical Operating Characteristics (Cont.)

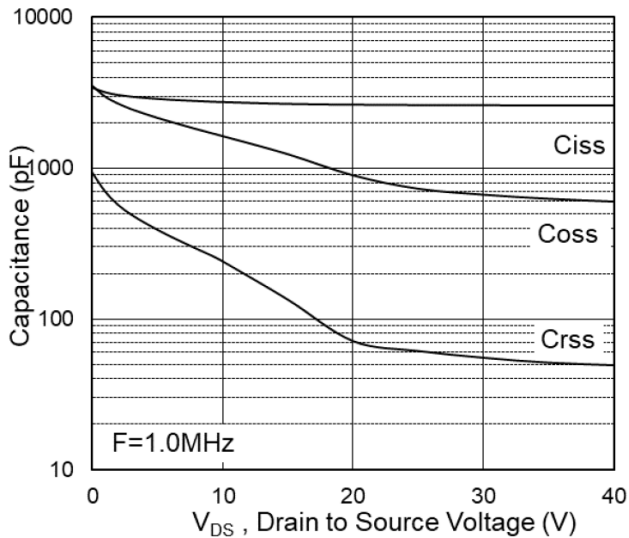


Fig.7 Capacitance

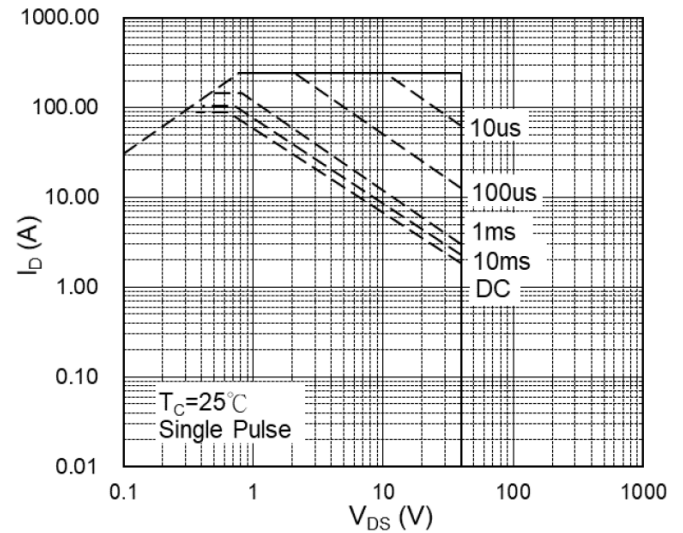


Fig.8 Safe Operating Area

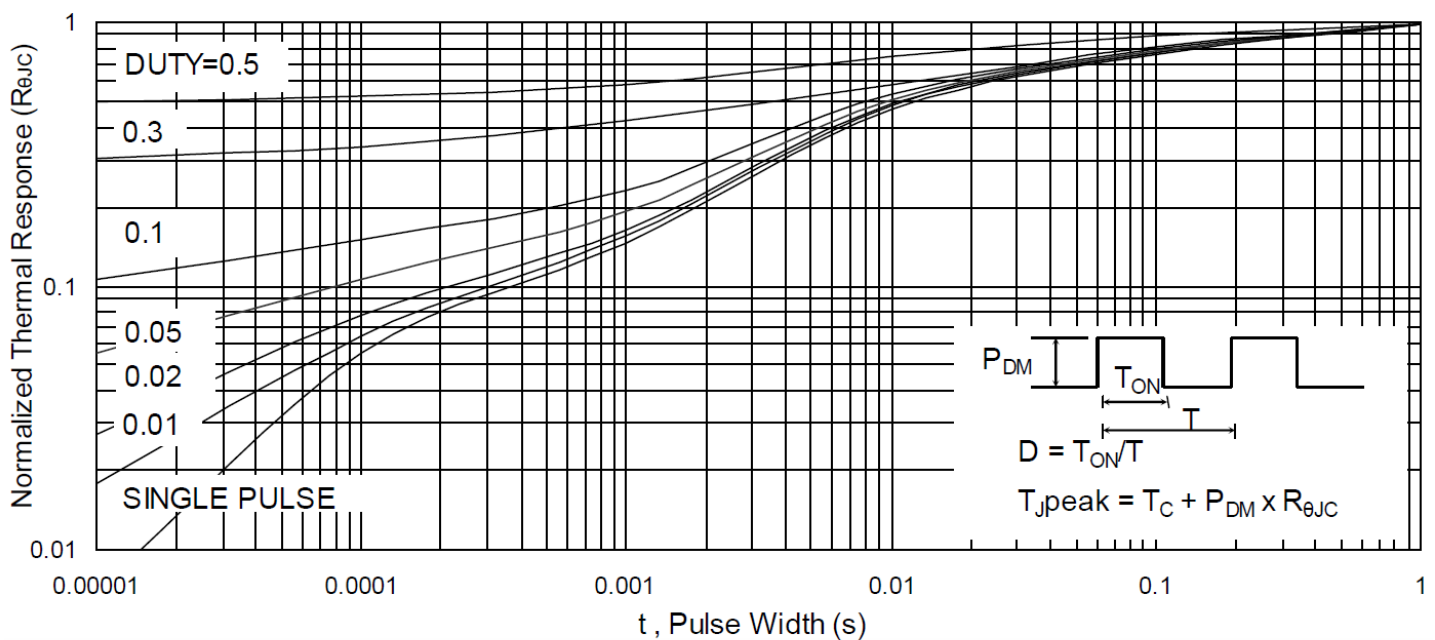


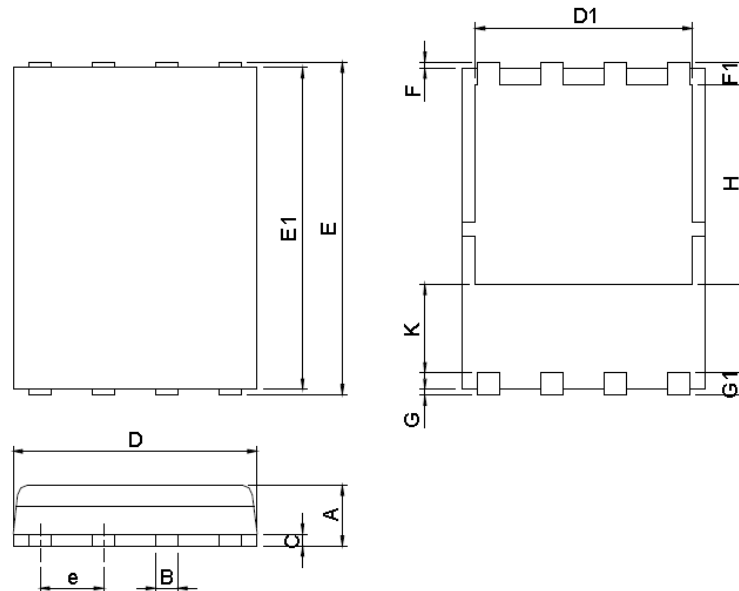
Fig.9 Normalized Maximum Transient Thermal Impedance

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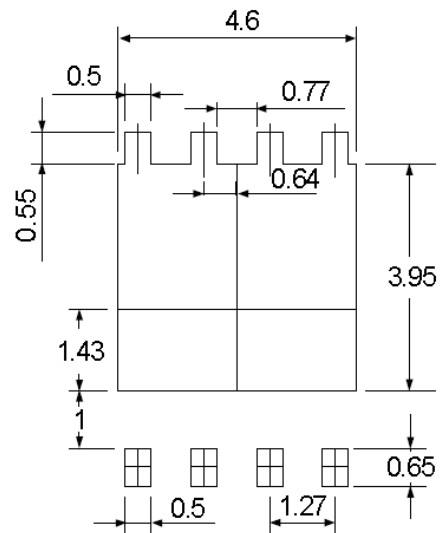
Package Information

DFN5*6-8 Package



SYMBOL	DFN5x6-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.

Design Notes